

L Number	Hits	Search Text	DB	Time stamp
1	3727	damascene	USPAT	2003/11/20 15:03
2	1009	damascene and barrier and electrode	USPAT	2003/11/20 15:33
3	781	((damascene and barrier and electrode) and (polishing or cmp or polished or planarize or planarizing) and (copper or cu)	USPAT	2003/11/20 09:50
4	582	((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu)))	USPAT	2003/11/20 09:50
5	193	((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor	USPAT	2003/11/20 09:50
6	169	((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor) and @ay<=2001	USPAT	2003/11/20 09:50
7	1968	damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)	USPAT	2003/11/20 12:12
8	1775	((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)	USPAT	2003/11/20 12:00
9	1160	((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench	USPAT	2003/11/20 12:01
10	858	((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)	USPAT	2003/11/20 12:01
11	141	((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene) and (capacitor or capacitive)	USPAT	2003/11/20 12:02
12	132	((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene) and (capacitor or capacitive)) and @ay<=2001	USPAT	2003/11/20 14:23
13	5	("5539231" "5702981" "5801094" "5891799" "5933761").PN.	USPAT	2003/11/20 12:09

14	846	damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)	USPAT	2003/11/20 12:13
15	741	(damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))	USPAT	2003/11/20 12:18
16	178	((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor	USPAT	2003/11/20 12:14
17	139	((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor) not ((((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001)	USPAT	2003/11/20 12:14
18	121	(((((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor) not ((((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001)) and @ay<=2001	USPAT	2003/11/20 12:14
19	59	(((((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor) not ((((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001)) and @ay<=2001) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor) and @ay<=2001)	USPAT	2003/11/20 12:14

33	380	(((((damascene or (via and trench)) and (barrier or liner or conformal)) and (polish or polishing or cmp or planarize or planarizing)) and (copper or Cu)) and (mask or photo\$lresist)) and capacitor	US-PGPUB	2003/11/20 14:40
34	213	(((((damascene or (via and trench)) and (barrier or liner or conformal)) and (polish or polishing or cmp or planarize or planarizing)) and (copper or Cu)) and (mask or photo\$lresist)) and capacitor) and @ay<=2001	US-PGPUB	2003/11/20 14:40
35	650	(((((damascene or (via and trench)) and (barrier or liner or conformal)) and (polish or polishing or cmp or planarize or planarizing)) and (copper or Cu)) and ((mask or photo\$lresist) with (trench or via))	US-PGPUB	2003/11/20 14:44
36	111	(((((damascene or (via and trench)) and (barrier or liner or conformal)) and (polish or polishing or cmp or planarize or planarizing)) and (copper or Cu)) and (mask or photo\$lresist)) and capacitor) and @ay<=2001) and ((mask or photo\$lresist) with (trench or via))	US-PGPUB	2003/11/20 14:52
37	1	6329324.pn.	USPAT	2003/11/20 14:53
38	1	6329234.pn.	USPAT	2003/11/20 15:14
39	14	("5194932" "5208726" "5293510" "5406447" "5675184" "5726083" "5879985" "5932906" "5946569" "5998276" "6146941" "6184076" "6258653" "6259128").PN.	USPAT	2003/11/20 14:54
42	15	("4481283" "4959705" "5065273" "5262354" "5322812" "5396094" "5406447" "5459100" "5479316" "5502000" "5576240" "5602053" "5858833" "5858834" "5861676").PN.	USPAT	2003/11/20 14:56
43	2671	((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$l or removing or etch or etching or etched))	USPAT	2003/11/20 15:05
44	886	((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$l or removing or etch or etching or etched))) and capacitor	USPAT	2003/11/20 15:05
45	460	((((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$l or removing or etch or etching or etched))) and capacitor) and (copper or Cu)	USPAT	2003/11/20 15:05
46	245	(((((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$l or removing or etch or etching or etched))) and capacitor) and (copper or Cu)) and ((mask or photo\$lresist) same (trench or via))	USPAT	2003/11/20 15:06

47	132	<p>(((((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$1 or removing or etch or etching or etched))) and capacitor) and (copper or Cu)) and ((mask or photo\$1resist) same (trench or via))) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor) or (((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001) or (((((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor) not (((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001)) and @ay<=2001))</p>	USPAT	2003/11/20 15:06
49	132	<p>(((((dual adj damascene) or (trench and via)) and ((barrier or liner or conformal) with (remove\$1 or removing or etch or etching or etched))) and capacitor) and (copper or Cu)) and ((mask or photo\$1resist) same (trench or via))) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor) or (((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001) or (((((damascene and (liner or conformal) and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) and ((dual adj damascene) or (trench and via))) and capacitor) not (((((damascene and barrier and (copper or Cu) and (polishing or polished or cmp or planarize or planarizing or planarized)) not (((damascene and barrier and electrode) and ((polishing or cmp or polished or planarize or planarizing) same (copper or cu))) and capacitor)) and via and trench) and (dual adj damascene)) and (capacitor or capacitive)) and @ay<=2001)) and @ay<=2001)) and @ay<=2002</p>	USPAT	2003/11/20 15:07

50	151	(damascene and barrier and electrode) and	USPAT	2003/11/20
-	3946	(Ir or Ru or ruthenium or iridium)	USPAT	15:34
-	1779	semiconductor and barrier and via and	USPAT	2003/11/20
-	1439	trench	USPAT	09:49
-	461	(semiconductor and barrier and via and	USPAT	2003/11/19
-	344	trench) and (Ta or tantalum)	USPAT	15:24
-	187	((semiconductor and barrier and via and	USPAT	2003/11/19
-	172	trench) and (Ta or tantalum)) and (polish	USPAT	15:23
-		or polishing or cmp or polished or		
-		planarize or planarizing)		
-		((semiconductor and barrier and via and	USPAT	2003/11/19
-		trench) and (Ta or tantalum)) and (polish	USPAT	15:23
-		or polishing or cmp or polished or		
-		planarize or planarizing)) and capacitor		
-		((semiconductor and barrier and via and	USPAT	2003/11/19
-		trench) and (Ta or tantalum)) and (polish	USPAT	15:24
-		or polishing or cmp or polished or		
-		planarize or planarizing)) and capacitor)		
-		and (copper or Cu)		
-		(((((semiconductor and barrier and via	USPAT	2003/11/19
-		and trench) and (Ta or tantalum)) and	USPAT	15:25
-		(polish or polishing or cmp or polished		
-		or planarize or planarizing)) and		
-		capacitor) and (copper or Cu)) and ((Ta		
-		or tantalum) with barrier)		
-		(((((semiconductor and barrier and via	USPAT	2003/11/19
-		and trench) and (Ta or tantalum)) and	USPAT	15:25
-		(polish or polishing or cmp or polished		
-		or planarize or planarizing)) and		
-		capacitor) and (copper or Cu)) and ((Ta		
-		or tantalum) with barrier)) and @ay<=2001		